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## ABSTRACT OF THE DISCLOSURE

By bringing an edge of encapsulation to the limit of a mounting portion and making the encapsulation smaller, a thermal head is miniaturized. In order to do that, a thermal head in which at least a part of a sealing portion has a surface cut in separation. Or, thermal heads are laid out on a wafer such that IC mounting portions of the thermal heads are adjacent to each other, A group of ICs adjacent to each other are simultaneously sealed, and then, the encapsulation portions are separated to obtain a single thermal head.